TRADEMARK ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	SECURITY INTEREST

CONVEYING PARTY DATA

Name	Formerly	Execution Date	Entity Type
Endicott Interconnect Technologies, Inc.		06/12/2013	CORPORATION: NEW YORK

RECEIVING PARTY DATA

Name:	William Maines
Street Address:	101 Broome Corporate Parkway
City:	Conklin
State/Country:	NEW YORK
Postal Code:	13748
Entity Type:	INDIVIDUAL: UNITED STATES

Name:	David Maines
Street Address:	101 Broome Corporate Parkway
City:	Conklin
State/Country:	NEW YORK
Postal Code:	13748
Entity Type:	INDIVIDUAL: UNITED STATES

PROPERTY NUMBERS Total: 8

Property Type	Number	Word Mark
Serial Number:	76657204	COREEZ
Serial Number:	76657205	COREEZ
Serial Number:	75333605	DRICLAD
Serial Number:	76476536	ENDICOTT INTERCONNECT
Serial Number:	85656675	
Serial Number:	85656712	ENDICOTT INTERCONNECT
Serial Number:	76476537	ENDICOTT INTERCONNECT TECHNOLOGIES
Serial Number:	75844816	HYPERBGA

OP $215.00 76657204

CORRESPONDENCE DATA

Fax Number: 6077236605

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.

Phone: 6077235341

Email: elawson@hhk.com

Correspondent Name: Hinman, Howard & Kattell - Erica Lawson

Address Line 1: 80 Exchange Street

Address Line 2: 700 Security Mutual Building

Address Line 4: Binghamton, NEW YORK 13901

ATTORNEY DOCKET NUMBER:	34107-529
NAME OF SUBMITTER:	Erica L. Lawson
Signature:	/Erica L. Lawson/
Date:	06/12/2013

Total Attachments: 23
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SECURITY AGREEMENT

1. SECURITY INTEREST. ENDICOTT INTERCONNECT TECHNOLOGIES, INC, a corporation organized under the law of the State of New York and having its chief executive office at 1093 Clark Street, Endicott, New York 13760 ("Debtor") hereby grants to WILLIAM MAINES and DAVID MAINES with an office at 101 Broome Corporate Parkway, Conklin, New York 13748 ("Secured Party") a continuing security interest ("Security Interest") in all property of Debtor described in Schedule A annexed to this Security Agreement (together with all amendments, supplements or other modifications, the "Agreement") hereto and made part hereof and on any separate schedule(s) at any time or from time to time furnished by Debtor to Secured Party, (all of which are hereby deemed part of this Agreement), in all supporting obligations thereof and in all increases or profits received therefrom, the software and books and records related thereto, and in all parts, accessories, special tools, attachments, additions, accessions, replacements and substitutions thereto or therefor, wherever located, whether now existing or hereafter acquired or created, and in all proceeds of all of the foregoing in any form (the "Collateral").

2. INDEBTEDNESS SECURED. The Security Interest granted by Debtor secures the full payment of all loans, advances, debts, liabilities, indebtedness, obligations, and credit of any kind or character owing by Debtor to Secured Party of any kind or nature, present or future, whether as borrower or guarantor, however evidenced, whether arising under this Agreement or any other loan, note, letter of credit, guaranty, collateral or other agreement or by operation of law, and whether direct or indirect, absolute or contingent, due or to become due, now owing or existing or hereafter arising or created and however acquired, and any amendments, extensions, renewals or increases thereof, including, without limitation, all principal, interest, charges, expenses, commitment or facility fees, collateral management or other fees, treasury management obligations, foreign exchange obligations, obligations due pursuant to any Interest Rate Protection Agreement entered into by Debtor, reasonable attorneys' fees and expenses related to the collection of the foregoing, and any other amounts payable by Debtor under this Agreement or any other agreements between Debtor and Secured Party whether executed in connection herewith or otherwise (collectively, the "Indebtedness"). "Interest Rate Protection Agreement" shall mean any agreement, device or arrangement designed to protect such Debtor from fluctuations of interest rates, exchange rates or forward rates, including, but not limited to, dollar-denominated or cross-currency exchange agreements, forward currency exchange agreements, interest rate caps, collars or floors, forward rate currency or interest rate options, puts, warrants, swaps, swaptions, U.S. Treasury locks and U.S. Treasury options, and any and all cancellations, buybacks, reversals, terminations or assignments of any of the foregoing.

3. REPRESENTATIONS AND WARRANTIES OF DEBTOR. Debtor represents and warrants, and so long as any Indebtedness remains unpaid shall be deemed continuously to represent and warrant, that:

(a) Debtor is the owner of the Collateral free and clear of all security interests, liens or other encumbrances, except the Security Interest in favor of Secured Party and any Permitted Lien identified on Schedule B attached hereto;

(b) Debtor has the power and authority to own the Collateral, to grant the Security Interest and to enter into and perform this Agreement and any other document or instrument delivered in connection herewith; and

(c) Except as may hereafter be disclosed in writing by Debtor to Secured Party, the Collateral is located at and used in connection with Debtor's business operations at the address(es) specified on Schedule B hereto, and Debtor's records concerning the Collateral are kept only at such address(es).

4. COVENANTS OF DEBTOR.

(a) Debtor will defend the Collateral against the claims and demands of all other parties including, without limitation, defenses, setoffs, claims and counterclaims asserted by any obligor against Debtor and/or Secured Party, will keep the Collateral free from all security interests, liens or other encumbrances, except for Permitted Liens, and will not sell, transfer, lease, assign, deliver or otherwise dispose of any Collateral or any interest therein without the prior written consent of Secured Party except for sales of Inventory in the ordinary course of Debtor's business;

(b) Debtor will keep, in accordance with generally accepted accounting principles consistently applied, accurate and complete records concerning the Collateral, and at Secured Party's request, Debtor will mark any and all such records to indicate the Security Interest and will permit Secured Party or its agents to inspect the Collateral and to audit and make extracts from such records or any of Debtor's books, ledgers, financial reports, correspondence or other records;

(c) Except in connection with Permitted Liens, Debtor will deliver to Secured Party, upon demand, any instruments, documents and chattel paper constituting, representing or relating to the Collateral or any part thereof and any schedules, invoices, shipping documents, delivery receipts, purchase orders, contracts or other documents representing or relating to the Collateral or any part thereof;

(d) Without thirty (30) days prior written notice to Secured Party, Debtor will not (i) change its business addresses or chief executive office, or (ii) make any change in Debtor's name, state of formation, identity or organizational status;

(e) Debtor will keep the Collateral in good condition, working order and repair and will not use the Collateral in violation of any provisions of this Agreement, any applicable law or governmental regulation or of any policy insuring the Collateral, unless the failure to so keep the Collateral will not have a material adverse effect on Debtor, the Collateral, or the business, operation, assets or affairs of Debtor;

(f) Debtor will (i) pay all taxes, assessments and other charges of every nature which may be levied or assessed against the Collateral other than taxes, assessments, fees and charges being contested in good faith by appropriate proceedings being diligently pursued and (ii) at all times keep the Collateral insured against loss, damage, theft and other risks, in such amounts, with such insurance carriers and under such form of policies as shall be reasonably acceptable to Secured Party, with appropriate endorsements designating Secured Party as lender loss payee and additional insured, as

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requested by Secured Party, and which policies of insurance shall provide that all losses thereunder shall be payable to Secured Party, as its interest may appear, and Secured Party may apply any proceeds of such insurance received by it toward payment of any of the Indebtedness, whether or not due, in such order of application as Secured Party may determine, and the original or duplicates of such policies of insurance or certificates thereof shall be delivered to Secured Party, on the date hereof, upon each renewal and upon its request; provided, however, that the rights hereunder are subject to the rights of any superior secured party;

(g) Debtor will not permit any part of the Collateral to be or become an accession to other goods not covered by this Agreement;

(h) If all or any part of the Collateral is located on property which is not owned by Debtor, Debtor will deliver to Secured Party for each such location a Landlord's Waiver; and

(i) Debtor will execute and deliver to Secured Party such certificates of title, assignments and other documents and will take such other actions relating to the Security Interest and the perfection thereof as Secured Party may reasonably request and will pay all costs of title searches and filing financing statements, certificates of title, assignments and other documents in all public offices requested by Secured Party.

(j) Debtor will make no payments to or on behalf of Integrian Holdings, LLC except in accordance with the Subordination Agreement of even date herewith by and between Integrian Holdings, LLC and Secured Party.

5. PROVISIONS RELATED TO ACCOUNTS. Subject to the rights of any superior secured party, Debtor irrevocably makes, constitutes and appoints Secured Party (and any of Secured Party's designated officers, employees or agents) as its true and lawful attorney in fact with power to sign its name and to take any of the following actions, in its name or in the name of Secured Party, as Secured Party may determine, at any time (except as expressly limited in this Section 5) without notice to Debtor and at Debtor's expense:

(a) Verify the validity and amount of, or any other matter relating to, the accounts with account debtors;

(b) Notify all account debtors that the accounts have been assigned to Secured Party and that Secured Party has a Security Interest in the accounts;

(c) Take control in any manner of any cash or noncash items of payment or proceeds of the accounts;

(d) In any case and for any reason, notify the United States Postal Service to change the addresses for delivery of mail addressed to Debtor to such address as Secured Party may designate;

(e) In any case and for any reason, receive, open and dispose of all mail addressed to Debtor; and

(f) Upon demand for repayment of the Indebtedness or upon the occurrence of an Event of Default, as applicable, enforce payment of and collect any accounts, by legal proceedings or otherwise, and for such purpose Secured Party may:

(i) Demand payment of any accounts or instruct any account debtors to make payment of accounts directly to Secured Party (whether to a lockbox account or otherwise);

(ii) Receive and collect all monies due or to become due to Debtor;

(iii) Exercise all of Debtor's rights and remedies with respect to the collection of the accounts;

(iv) Settle, adjust, compromise, extend, renew, discharge or release the accounts;

(v) Endorse the name of Debtor upon any chattel papers, documents, instruments, invoices, freight bills, bills of lading or similar documents or agreements relating to accounts or goods pertaining to accounts or upon any checks or other medium of payment or evidence of security interest that may come into Secured Party's possession;

(vi) Sign the name of Debtor to verifications of accounts sent by account debtors to Debtor; or

(vii) Take all other actions necessary or desirable to protect Debtor's interest(s) in the accounts.

Debtor irrevocably authorizes and directs each account debtor to honor any demand by Secured Party that all payments in respect of the accounts thereafter be paid directly to Secured Party. In each such case account debtor may continue directing all such payments to Secured Party until account debtor shall have received written notice from Secured Party either that the Indebtedness has been paid in full or that Secured Party has released its security interest. No account debtor shall have any responsibility to inquire into Secured Party's right to make any such demand or to follow Secured Party's disposition of any moneys paid to Secured Party by account debtor.

Debtor further agrees to use its best efforts to assist Secured Party in the collection and enforcement of the accounts and will not hinder, delay or impede Secured Party in any manner in its collection and enforcement of the accounts.

6. VERIFICATION OF COLLATERAL. Secured Party shall have the right to verify all or any Collateral in any manner and through any medium Secured Party may consider appropriate, and Debtor agrees to furnish all assistance and information and perform any acts which Secured Party may reasonably require in connection therewith. In furtherance thereof, Debtor agrees to provide to Secured Party, without request or demand from Secured Party, monthly and quarterly unaudited balance sheet and unaudited statements of income and cash flow reflecting results of operations within thirty (30) days of the end of each month and quarter. Such financial information shall be complete and accurate in all material respects.

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7. NOTIFICATION AND PAYMENTS. Secured Party may notify Debtor in writing, at any time after demand or the occurrence of an Event of Default as defined in the Term Note, as applicable, and without waiving in any manner the Security Interest, that any payments on account of and from the Collateral received by Debtor (a) shall be held by Debtor in trust for Secured Party in the same medium in which received, (b) shall not be commingled with any assets of Debtor and (c) shall be turned over to Secured Party not later than the next business day following the day of their receipt.

8. MISCELLANEOUS.

(a) Debtor hereby appoints Secured Party as attorney-in-fact of Debtor, irrevocably and with power of substitution, in the same manner, to the same extent and with the same effect as if Debtor were to do the same to file financing statements relating to the Collateral or to execute and file any such financing statement in Debtor's name, all as Secured Party may deem appropriate to perfect and continue the Security Interest; upon demand or the occurrence and during the continuance of an Event of Default (i) to make, adjust or settle and receive payment on any insurance claims with respect to the Collateral; (ii) to endorse the name of Debtor on any instruments, documents or other evidences of the Collateral that may come into Secured Party's possession; (iii) to execute proofs of claim and loss or similar documents; (iv) to execute endorsements, assignments or other instruments of sale, conveyance or transfer for any Collateral; and (v) to perform all other acts which Secured Party deems appropriate to protect and preserve the Collateral and to enforce the terms of this Agreement. Debtor ratifies and approves all acts of said attorney-in-fact and agrees that said attorney shall not be liable for any acts of commission or omission, nor for any error of judgment or mistake of fact or law. This power, being coupled with an interest, is unconditional and irrevocable until the Indebtedness is paid in full and Debtor shall have performed all of its obligations under this Agreement.

(b) Upon Debtor's failure to perform any of its covenants or obligations hereunder, Secured Party may, but shall not be obligated to, perform any or all such covenants or obligations, and Debtor shall pay an amount equal to the expense thereof to Secured Party upon demand by Secured Party, and all such amounts shall become part of the Indebtedness secured hereby.

(c) No course of dealing and no delay or omission by Secured Party in exercising any right or remedy hereunder or with respect to any Indebtedness shall operate as a waiver thereof or of any other right or remedy, and no single or partial exercise thereof shall preclude any other or further exercise thereof or the exercise of any other right or remedy. Secured Party may remedy any default by Debtor hereunder or with respect to any Indebtedness in any reasonable manner without waiving the default remedied and without waiving any other prior or subsequent default by Debtor. All rights and remedies of Secured Party hereunder are cumulative, and are in addition to any and all rights and remedies available to Secured Party under the Uniform Commercial Code and other applicable law in effect from time to time.

(d) Secured Party shall have no obligation to take, and Debtor shall have the sole responsibility for taking, any and all steps to preserve rights against any and all prior parties to any instrument or chattel paper constituting Collateral whether or not in

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Secured Party's possession. Secured Party shall not be responsible to Debtor for loss or damage resulting from Secured Party's failure to enforce or collect any Collateral or to collect any moneys due or to become due thereunder. Debtor waives protest of any instrument constituting Collateral at any time held by Secured Party on which Debtor is in any way liable and waives notice of any other action taken by Secured Party.

(e) Without limiting its rights of setoff under New York law generally, upon and at any time and from time to time after demand or any occurrence or existence of any Event of Default, Secured Party shall have the right to place an administrative hold on, and setoff against each obligation of Debtor pursuant to this Agreement, each obligation of Secured Party or any affiliate of Secured Party (in any capacity) owing to Debtor, whether now existing or hereafter arising or accruing, whether or not then due and whether pursuant to any Deposit Account or certificate of deposit or in any other manner. Such setoff shall become effective at the time Secured Party determines even though evidence thereof is not entered in the records of Secured Party until later.

(f) To the extent Debtor directly receives any remittances upon any Accounts, Debtor will, at Debtor's sole cost and expense, but on Secured Party's behalf and for Secured Party's account, and subject in all instances to the rights of any superior secured party, collect as Secured Party's property and in trust for Secured Party, all amounts received on Accounts, and shall not commingle such collections with any Debtor's funds or use the same except to pay amounts due Secured Party.

(g) The rights and benefits of Secured Party hereunder shall, if Secured Party so agrees, inure to any party acquiring any interest in the Indebtedness or any part thereof.

(h) Secured Party and Debtor shall include the heirs, distributees, executors or administrators, or successors or assigns, of those parties.

(i) No modification, rescission, waiver, release or amendment of any provision of this Agreement shall be binding except by a written agreement subscribed by Debtor and by a duly authorized officer of Secured Party.

(j) This Agreement and the transaction evidenced hereby shall be construed under the laws of New York State as the same may from time to time be in effect. All terms defined in the Uniform Commercial Code, unless otherwise defined in this Agreement or in any financing statement, shall have the definitions set forth in the Uniform Commercial Code adopted in New York State as in effect on the date of this Agreement and as the same may be amended, modified or supplemented from time to time. If any term of this Agreement shall be held to be invalid, illegal or unenforceable, the validity of all other terms hereof shall in no way be affected thereby.

(k) This Agreement is and is intended to be a continuing Security Agreement and shall remain in full force and effect until all of the Indebtedness and any extensions or renewals thereof shall be paid in full.

(l) To the fullest extent permitted by applicable law, Debtor shall not assert, and hereby waives any claim against Secured Party, on any theory of liability, for

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special, indirect, consequential or punitive damages (but excluding direct or actual damages) arising out of, in connection with or as a result of, this Agreement, any related loan documents, the transactions contemplated hereby or thereby or any loan or the use of the proceeds.

9. CONSENTS AND WAIVERS RELATING TO LEGAL PROCEEDINGS.

(a) DEBTOR KNOWINGLY, VOLUNTARILY, INTENTIONALLY AND IRREVOCABLY (i) CONSENTS IN EACH ACTION AND OTHER LEGAL PROCEEDING COMMENCED BY SECURED PARTY AND ARISING OUT OF OR OTHERWISE RELATING TO THIS AGREEMENT, ANY OF THE OBLIGATIONS, ANY OF THE COLLATERAL OR ANY OTHER COLLATERAL TO THE JURISDICTION OF ANY COURT THAT IS EITHER A COURT OF RECORD OF THE STATE OF NEW YORK OR A COURT OF THE UNITED STATES LOCATED IN THE STATE OF NEW YORK AND (ii) WAIVES EACH OBJECTION TO THE LAYING OF VENUE OF ANY SUCH ACTION OR OTHER LEGAL PROCEEDING.

(b) DEBTOR KNOWINGLY, VOLUNTARILY, INTENTIONALLY AND IRREVOCABLY WAIVES EACH RIGHT DEBTOR MAY HAVE TO A TRIAL BY JURY WITH RESPECT TO, AND IN, ANY ACTION OR OTHER LEGAL PROCEEDING OF ANY NATURE, RELATING TO (i) THIS AGREEMENT, ANY RELATED LOAN DOCUMENT OR ANY COLLATERAL, (ii) ANY TRANSACTION CONTEMPLATED BY ANY SUCH DOCUMENT OR (iii) ANY NEGOTIATION, PERFORMANCE OR ENFORCEMENT OF THIS AGREEMENT, OR ANY COLLATERAL. DEBTOR CERTIFIES THAT NEITHER SECURED PARTY NOR ANY REPRESENTATIVE THEREOF HAS REPRESENTED TO DEBTOR THAT SECURED PARTY WILL NOT SEEK TO ENFORCE THE WAIVER MADE BY DEBTOR IN THIS SECTION. DEBTOR ACKNOWLEDGES THAT IT HAS BEEN REPRESENTED BY INDEPENDENT LEGAL COUNSEL AS NECESSARY AND APPROPRIATE.

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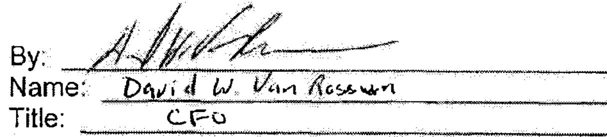
Dated this 12th day of June 2013.

ENDICOTT INTERCONNECT TECHNOLOGIES, INC



By: ______________________
Name: David W. Van Rossum
Title: CFO

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SCHEDULE A

All terms, unless otherwise defined in this Agreement or in any financing statement, shall have the definitions set forth in the Uniform Commercial Code adopted in New York State, as in effect on the date of this Agreement and as may be amended, modified or supplemented from time to time.

"**Collateral**" includes all of Debtor's accounts, equipment, inventory, fixtures, general intangibles, chattel paper, instruments, documents, goods, deposit accounts, investment property, letters of credit and letter-of-credit rights, supporting obligations, commercial tort claims (if any, as described), insurance proceeds, and property in Secured Party's control or possession, software, books and records, all attachments, replacements, substitutions, and the proceeds of all the foregoing.

"**Collateral**" includes all of Debtor's right, title and interest in the following, wherever located and whether now existing or hereafter acquired or created and all proceeds thereof:

- ☑ **Accounts**
- ☑ **Inventory**
- ☑ **Equipment**
- ☑ **Fixtures**
- ☑ **General Intangibles**
- ☑ **Chattel Paper**
- ☑ **Documents**
- ☑ **Instruments**
- ☑ **Deposit Accounts**
- ☑ **Patents and Trademarks**

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Trademark/Service Mark	Country	Filing Date	Application No.	Registration No.	Registration Date	Status
COREEZ	US	3/24/2006	76/657,204	3,619,679	5/12/2009	Registered; Declaration of Use Due 5/12/2015
CoreEZ	US	3/24/2006	76/657,205	3,564,994	1/20/2009	Registered; Declaration of Use Due 1/20/2015
DRICLAD	US	7/31/1997	75/333,605	2,594,509	7/16/2002	Registered; Renewal Due 7/16/2022
DRICLAD	Brazil	1/22/1998	820508039	820508039	1/27/2009	Registered; Renewal Due 1/27/2019
DRICLAD	China		9800105902	1435500	8/21/2000	Registered; Renewal Due 8/20/2020
DRICLAD	France	5/9/2000		721563	7/23/2001	Registered; Renewal Due 12/30/2017
DRICLAD	Japan	11/14/1997	H09-177086	4245007	2/26/1999	Registered; Renewal Due 8/26/2018
DRICLAD	Korea	9/10/1998	1998-0023497	456079	9/29/1999	Registered; Renewal Due 10/6/2019
DRICLAD	Mexico	1/30/1998		572578		Registered; Renewal Due 1/30/2018
DRICLAD	Taiwan			108344		Registered; Renewal Due 7/15/2020
DRICLAD	Taiwan			896915		Registered; Renewal Due 3/31/2019
Endicott Interconnect	US	12/16/2002	76/476,536	2,831,497	4/13/2004	Registered
ENDICOTT INTERCONNECT 3D Design Only	US	6/20/2012	85/656,675			Pending
ENDICOTT INTERCONNECT 3D Design Only	UK	8/13/2012	2631552			Pending
ENDICOTT INTERCONNECT and 3D Design	US	6/20/2012	85/656,712			Pending
ENDICOTT INTERCONNECT and 3D Design	UK	8/13/2012	2631295			Pending
Endicott Interconnect Technologies	US	12/16/2002	76/476,537	2,829,453	4/6/2004	Registered; Renewal Due 4/6/2014
HYPERBGA	US	11/9/1999	75/844,816	2,632,339	10/8/2002	Registered; Renewal Due 10/8/2022
HYPERBGA	Australia	2/24/2000	824959	824959	2/16/2001	Registered; Renewal Due 2/24/2020
HYPERBGA	Canada	8/10/2004	1226508	TMA642449	6/20/2005	Registered; Renewal Due 12/20/2019
HYPERBGA	Canada		1044049			Registered; Renewal Due 6/19/2020
HYPERBGA	Singapore		TOO/10304A	T00/10304A	6/14/2000	Registered; Renewal Due 6/14/2020
HYPERBGA	Switzerland			477543		Registered; Renewal Due 5/5/2020
HYPERBGA	Taiwan			950034		Registered; Renewal Due 7/5/2021
HYPERBGA	Europe	5/9/2000	1645605	1645605	7/23/2001	Registered; Renewal Due 5/9/2020

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Docket No.	Country	Title	Filing Date	Appl. No.	Publication No.	Issued	Patent No.	Status
2-03-002	United States	CIRCUITIZED SUBSTRATE AND METHOD OF MAKING SAME	2/24/2003	10/370,529	2004-0163964	6/14/2005	6,905,589	Issued
CA-2-03-002	Canada	CIRCUITIZED SUBSTRATE AND METHOD OF MAKING SAME		2452178			2,452,178	Issued
2-02-001	US	CIRCUITIZED SUBSTRATE ASSEMBLY AND METHOD OF MAKING SAME	12/19/2002	10/322,527	2004-0118596	10/26/2004	6,809,269	Issued
CA-2-02-001	Canada	CIRCUITIZED SUBSTRATE ASSEMBLY AND METHOD OF MAKING SAME	12/5/2003	2452178		5/13/2008	2,452,178	Issued
CN-2-02-001	China	CIRCUITIZED SUBSTRATE ASSEMBLY AND METHOD OF MAKING SAME	12/19/2003	200310123253.X			ZL20031012 3253	Issued
2-02-001-CIP	US	INFORMATION HANDLING SYSTEM UTILIZING CIRCUITIZED SUBSTRATE	3/6/2003	10/379,575	2004-0118598	3/29/2005	6,872,894	Issued
2-02-001-CIPD	US	INFORMATION HANDLING SYSTEM UTILIZING CIRCUITIZED SUBSTRATE	9/3/2004	10/933,260	2005-0023035	5/31/2005	6,900,392	Issued
2-02-001D	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE ASSEMBLY	3/30/2004	10/811,915	2004-0177998	5/23/2006	7,047,630	Issued
2-02-001D2	US	CIRCUITIZED SUBSTRATE ASSEMBLY AND METHOD OF MAKING SAME	8/11/2004	10/915,483	2005-0011670	7/4/2006	7,071,423	Issued
2-02-001D3	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE ASSEMBLY	2/9/2006	11/349,998	2006-0123626	3/18/2008	7,343,674	Issued
CA-2-03-001	Canada	HIGH SPEED CIRCUIT BOARD AND METHOD FOR FABRICATION	12/29/2003	2454289		5/13/2008	2,454,289	Issued
TW-2-03-001	Taiwan	HIGH SPEED CIRCUIT BOARD AND METHOD FOR FABRICATION		93101219				Issued
2-03-001-CIP1	US	MULTI-CHIP ELECTRONIC PACKAGE HAVING LAMINATE CARRIER AND METHOD OF MAKING SAME	3/24/2003	10/394,107	2004-0150114	4/25/2006	7,035,113	Issued
2-03-001-CIP2	US	INFORMATION HANDLING SYSTEM	3/24/2003	10/394,135	2004-0150101	4/4/2006	7,023,707	Issued
2-03-001D	US	METHOD OF MAKING HIGH SPEED CIRCUIT BOARD	3/30/2004	10/811,817	2004-0231888	12/26/2006	7,152,319	Issued
2-03-007	US	METHOD OF TESTING SPACINGS IN PATTERN OF OPENINGS IN PCB CONDUCTIVE LAYER	7/11/2003	10/616,932	2005-0005438	3/21/2006	7,013,563	Issued
2-03-003	US	MATERIAL SEPARATION TO FORM SEGMENTED PRODUCT	4/9/2003	10/409,066	2004-0201136	10/25/2005	6,958,106	Issued
2-03-011	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE	10/7/2003	10/679,302	2005-0074924	8/1/2006	7,084,014	Issued
2-03-011D1	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE	10/26/2005	11/258,092	2006-0040426	1/16/2007	7,163,847	Issued
2-03-011D2	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE	10/27/2005	11/259,043	2006-0046462	8/15/2006	7,091,066	Issued
2-03-009	US	CIRCUITIZED SUBSTRATE AND METHOD OF MAKING SAME	8/20/2003	10/643,909	2005-0039840	6/20/2006	7,063,762	Issued
2-03-009D	US	CIRCUITIZED SUBSTRATE WITH CONDUCTIVE POLYMER AND SEED MATERIALS ADHESION LAYER	10/5/2005	11/242,841	2006-0029781	2/19/2008	7,332,212	Issued
2-03-008	US	ELECTRONIC COMPONENT TEST APPARATUS	7/31/2003	10/630,722	2005-0022376	9/19/2006	7,109,732	Issued
TW-2-03-006	Taiwan	ELECTRONIC CARD		93114136				Pending
2-03-004-CIP	US	ELECTRONIC PACKAGE WITH STRENGTHENED CONDUCTIVE PAD	4/28/2003	10/423,877	2004-0183212	11/9/2004	6,815,837	Issued
EP-2-03-004-CIP	Europe	ELECTRONIC PACKAGE WITH STRENGTHENED CONDUCTIVE PAD		4250754.1				Pending
TW-2-03-004-CIP	Taiwan	ELECTRONIC PACKAGE WITH STRENGTHENED CONDUCTIVE PAD	2/11/2004	93103172		8/1/2007	I284967	Issued
2-03-005-CIP	US	PINNED ELECTRONIC PACKAGE WITH STRENGTHENED CONDUCTIVE PAD	4/28/2003	10/423,972	2004-082604	8/8/2006	7,087,846	Issued
2-05-002	US	ELECTRONIC CARD ASSEMBLY	3/23/2005	11/086,324	2006-0213973	10/28/2008	7,441,709	Issued
2-04-003	US	CIRCUITIZED SUBSTRATE	3/31/2004	10/812,890	2005-0224985	7/18/2006	7,078,816	Issued
EP-2-04-003	Europe	CIRCUITIZED SUBSTRATE		5251748.9				Pending
2-04-003D1	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE	2/9/2006	11/349,990	2006-0131755	8/26/2008	7,416,996	Issued
2-04-003D2	US	INFORMATION HANDLING SYSTEM UTILIZING A CIRCUITIZED SUBSTRATE HAVING A DIELECTRIC LAYER WITHOUT CONTINUOUS FIBERS	2/10/2006	11/350,777	2006-0125103	3/24/2009	7,508,076	Issued
2-04-005	US	DIELECTRIC COMPOSITION FOR FORMING DIELECTRIC LAYER FOR USE IN CIRCUITIZED SUBSTRATES	3/31/2004	10/812,889	2008-0008727	9/18/2007	7,270,845	Issued
EP-2-04-005	Europe	DIELECTRIC COMPOSITION FOR FORMING DIELECTRIC LAYER FOR USE IN CIRCUITIZED SUBSTRATES		5251747.1				Pending
TW-2-04-005	Taiwan	DIELECTRIC COMPOSITION FOR FORMING DIELECTRIC LAYER FOR USE IN CIRCUITIZED SUBSTRATES	3/18/2005	94108442				Pending

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Docket No.	Country	Title	Filing Date	Appl. No.	Publication No.	Issued	Patent No.	Status
2-04-005D	US	CIRCUITIZED SUBSTRATE WITH DIELECTRIC LAYER HAVING DIELECTRIC COMPOSITION NOT INCLUDING CONTINUOUS OR SEMI-CONTINUOUS FIBERS	9/6/2007	11/896,786	2008-0003407			Allowed
2-03-001-CIP3	US	STACKED CHIP ELECTRONIC PACKAGE HAVING LAMINATE CARRIER AND METHOD OF MAKING SAME	9/15/2003	10/661,616	2004-0150095	1/31/2006	6,992,896	Issued
TW-2-03-001-CIP3	Taiwan	STACKED CHIP ELECTRONIC PACKAGE HAVING LAMINATE CARRIER AND METHOD OF MAKING SAME		93101178				Issued
2-03-001-CIP3C	US	STACKED CHIP ELECTRONIC PACKAGE HAVING LAMINATE CARRIER AND METHOD OF MAKING SAME	9/30/2005	11/238,960	2006-0023439	1/9/2007	7,161,810	Issued
2-03-001-CIP3CD	US	METHOD OF MAKING A MULTI-CHIP ELECTRONIC PACKAGE HAVING LAMINATE CARRIER	6/19/2006	11/455,183	2006-0240594	2/23/2010	7,665,207	Issued
2-04-011	US	CIRCUITIZED SUBSTRATE WITH INTERNAL ORGANIC MEMORY DEVICE, ELECTRICAL ASSEMBLY UTILIZING SAME, AND INFORMATION HANDLING SYSTEM UTILITIZING SAME	7/28/2004	10/900,385	2006-0022303	8/7/2007	7,253,502	Issued
TW-2-04-011		CIRCUITIZED SUBSTRATE WITH INTERNAL ORGANIC MEMORY DEVICE, METHOD OF MAKING SAME, ELECTRICAL ASSEMBLY UTILIZING SAME AND INFORMATION HANDLING SYSTEM UTILIZING SAME		94124018				Pending
2-04-011D	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE WITH INTERNAL ORGANIC MEMORY DEVICE	6/12/2007	11/808,596	2007-0249089	2/5/2008	7,326,643	Issued
2-04-014	US	ELECTRICAL ASSEMBLY WITH INTERNAL MEMORY CIRCUITIZED SUBSTRATE HAVING ELECTRONIC COMPONENTS POSITIONED THEREON, METHOD OF MAKING SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME	7/28/2004	10/900,386	2006-0022310	5/16/2006	7,045,897	Issued
2-07-011	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE WITH INTERNAL OPTICAL PATHWAY	10/9/2007	11/907,006	2009-0092353	6/2/2009	7,541,058	Issued
CN-2-07-011	China	METHOD OF MAKING CIRCUITIZED SUBSTRATE WITH INTERNAL OPTICAL PATHWAY		200810168239.4				Pending
2-07-014	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE WITH INTERNAL OPTICAL PATHWAY USING PHOTOLITHOGRAPHY	10/19/2007	11/907,004	2009-0093073	5/11/2010	7,713,767	Issued
CN-2-07-014	China	METHOD OF MAKING CIRCUITIZED SUBSTRATE WITH INTERNAL OPTICAL PATHWAY USING PHOTOLITHOGRAPHY	10/6/2008	200810168238.X				Pending
2-07-012	US	CIRCUITIZED SUBSTRATE WITH INTERNAL COOLING STRUCTURE AND ELECTRICAL ASSEMBLY UTILIZING SAME	10/25/2007	11/976,468	2009-0109624	6/15/2010	7,738,249	Issued
CN-2-07-012	China	CIRCUITIZED SUBSTRATE WITH INTERNAL COOLING STRUCTURE AND ELECTRICAL ASSEMBLY UTILIZING SAME	10/22/2008	200810171145.2				Pending
2-03-012	US	ITEM IDENTIFICATION CONTROL METHOD	12/22/2003	10/740,500	2005-0137890	9/21/2010	7,801,833	Issued
2-04-004	US	LOW MOISTURE ABSORPTIVE CIRCUITIZED SUBSTRATE, METHOD OF MAKING SAME, ELECTRICAL ASSEMBLY UTILIZING SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME	8/18/2004	10/920,235	2005-0224251	12/5/2006	7,145,221	Issued
2-04-007	US	LOW MOISTURE ABSORPTIVE CIRCUITIZED SUBSTRATE WITH REDUCED THERMAL EXPANSION, METHOD OF MAKING SAME, ELECTRICAL ASSEMBLY UTILIZING SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME	3/23/2005	11/086,323	2005-0218524	12/30/2008	7,470,990	Issued
CN-2-04-007	China	LOW MOISTURE ABSORPTIVE CIRCUITIZED SUBSTRATE WITH REDUCED THERMAL EXPANSION, METHOD OF MAKING SAME, ELECTRICAL ASSEMBLY UTILIZING SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME		200610057200.6				Pending

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Docket No.	Country	Title	Filing Date	Appl. No.	Publication No.	Issued	Patent No.	Status
EP-2-04-007	Europe	LOW MOISTURE ABSORPTIVE CIRCUITIZED SUBSTRATE WITH REDUCED THERMAL EXPANSION, METHOD OF MAKING SAME, ELECTRICAL ASSEMBLY UTILIZING SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME		6251492.2				Pending
IN-2-04-007	India	LOW MOISTURE ABSORPTIVE CIRCUITIZED SUBSTRATE WITH REDUCED THERMAL EXPANSION, METHOD OF MAKING SAME, ELECTRICAL ASSEMBLY UTILIZING SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME		355/DEL/2006				Pending
TW-2-04-007	Taiwan	LOW MOISTURE ABSORPTIVE CIRCUITIZED SUBSTRATE WITH REDUCED THERMAL EXPANSION, METHOD OF MAKING SAME, ELECTRICAL ASSEMBLY UTILIZING SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME		95108059				Pending
2-04-007D	US	METHOD OF MAKING SAME LOW MOISTURE ABSORPTIVE CIRCUITIZED SUBSTRATE WITH REDUCED THERMAL EXPANSION	4/5/2007	11/730,942	2007-0182016	8/26/2008	7,416,972	Issued
2-07-016	US	METHOD OF MAKING CIRCUITIZED SUBSTRATES HAVING FILM RESISTORS AS PART THEREOF	1/16/2008	12/007,820	2009-0178271	8/14/2012	8,240,027	Issued
2-05-020	US	CIRCUITIZED SUBSTRATE WITH SHIELDED SIGNAL LINES AND PLATED-THRU-HOLES AND METHOD OF MAKING SAME, AND ELECTRICAL ASSEMBLY AND INFORMATION HANDLING SYSTEM UTILIZING SAME	4/11/2006	11/401,401	2006-0214010	3/16/2010	7,679,005	Issued
2-05-022	US	METHOD OF MAKING PRINTED CIRCUIT BOARD WITH VARYING DEPTH CONDUCTIVE HOLES ADAPTED FOR RECEIVING PINNED ELECTRICAL COMPONENTS	1/19/2006	11/334,445	2006-0121722			Pending
2-03-013	US	PRINTED CIRCUIT BOARD WITH LOW CROSS-TALK NOISE	12/22/2003	10/740,398	2005-0133257	2/13/2007	7,176,383	Issued
EP-2-03-013	Europe	PRINTED CIRCUIT BOARD WITH LOW CROSS-TALK NOISE		4257721.3				Pending
JP-2-03-013	Japan	PRINTED CIRCUIT BOARD WITH LOW CROSS-TALK NOISE		2004-349471				Pending
TW-2-03-013	Taiwan	PRINTED CIRCUIT BOARD WITH LOW CROSS-TALK NOISE		93138054				Pending
2-03-013D	US	METHOD OF MAKING A PRINTED CIRCUIT BOARD WITH LOW CROSS-TALK NOISE	12/6/2006	11/634,287	2007-0089290	5/12/2009	7,530,167	Issued
2-03-014	US	METHOD OF MAKING MULTILAYERED PRINTED CIRCUIT BOARD WITH FILLED CONDUCTIVE HOLES	12/18/2003	10/737,974	2005-0136646	5/1/2007	7,211,289	Issued
JP-2-03-014	Japan	METHOD OF PROVIDING PRINTED CIRCUIT BOARD WITH CONDUCTIVE HOLES AND BOARD RESULTING THEREFROM		2004-355230				Pending
TW-2-03-014	Taiwan	METHOD OF PROVIDING PRINTED CIRCUIT BOARD WITH CONDUCTIVE HOLES AND BOARD RESULTING THEREFROM	12/3/2004	93137509		1/1/2012	I355871	Pending
2-03-014D	US	METHOD OF PROVIDING PRINTED CIRCUIT BOARD WITH CONDUCTIVE HOLES AND BOARD RESULTING THEREFROM	4/5/2006	11/397,713	2006-0183316	3/25/2008	7,348,677	Issued
2-04-002	US	CIRCUITIZED SUBSTRATE WITH SIGNAL WIRE SHIELDING, ELECTRICAL ASSEMBLY UTILIZING SAME AND METHOD OF MAKING	3/3/2004	10/790,747	2005-0195585	4/24/2007	7,209,368	Issued
2-04-002D	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE WITH SIGNAL WIRE SHIELDING	5/9/2006	11/429,990	2006-0200977	12/9/2008	7,478,472	Issued
2-04-009	US	CIRCUITIZED SUBSTRATE WITH FILLED ISOLATION BORDER, METHOD OF MAKING SAME, ELECTRICAL ASSEMBLY UTILIZING SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME	7/2/2004	10/882,170	2006-0000639	1/2/2007	7,157,647	Issued
2-04-009D1	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE WITH FILLED ISOLATION BORDER	7/10/2006	11/482,945	2006-0248717	10/19/2010	7,814,649	Issued
2-04-013	US	CIRCUITIZED SUBSTRATE WITH SPLIT CONDUCTIVE LAYER, METHOD OF MAKING SAME, ELECTRICAL ASSEMBLY UTILIZING SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME	7/2/2004	10/882,167	2006-0000636	1/2/2007	7,157,646	Issued

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Docket No.	Country	Title	Filing Date	Appl. No.	Publication No.	Issued	Patent No.	Status
IN-2-04-013	India	CIRCUITIZED SUBSTRATE WITH SPLIT CONDUCTIVE LAYER, METHOD OF MAKING SAME, ELECTRICAL ASSEMBLY UTILIZING SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME		1330/DEL/2005				Pending
TW-2-04-013	Taiwan	CIRCUITIZED SUBSTRATE WITH SPLIT CONDUCTIVE LAYER, METHOD OF MAKING SAME, ELECTRICAL ASSEMBLY UTILIZING SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME	6/20/2005	94120469		10/1/2012	I373992	Issued
2-04-013D	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE WITH SPLIT CONDUCTIVE LAYER AND INFORMATION HANDLING SYSTEM UTILIZING SAME	12/20/2006	11/641,810	2007-0144772	5/27/2008	7,377,033	Issued
2-04-013DD	US	INFORMATION HANDLING SYSTEM UTILIZING CIRCUITIZED SUBSTRATE WITH SPLIT CONDUCTIVE LAYER	1/18/2008	12/010,004	2008-0117583	2/17/2009	7,491,896	Issued
2-04-016	US	METHOD OF MAKING CIRCUITIZED SUBSTRATES UTILIZING SMOOTH-SIDED CONDUCTIVE LAYERS AS PART THEREOF	11/19/2004	10/991,532	2006-0110898	6/10/2008	7,383,629	Issued
CN-2-04-016	China	CIRCUITIZED SUBSTRATES UTILIZING SMOOTH-SIDED CONDUCTIVE LAYERS AS PART THEREOF, METHOD OF MAKING SAME, AND ELECTRICAL ASSEMBLIES AND INFORMATION HANDLING SYSTEMS UTILIZING SAME		200510115609.4				Pending
IN-2-04-016	India	CIRCUITIZED SUBSTRATES UTILIZING SMOOTH-SIDED CONDUCTIVE LAYERS AS PART THEREOF, METHOD OF MAKING SAME, AND ELECTRICAL ASSEMBLIES AND INFORMATION HANDLING SYSTEMS UTILIZING SAME		2488/DEL/20058				Pending
2-04-016D	US	CIRCUITIZED SUBSTRATES UTILIZING SMOOTH-SIDED CONDUCTIVE LAYERS AS PART THEREOF	4/17/2008	12/148,271	2008-0259581	11/23/2010	7,838,776	Issued
2-04-016D2	US	CIRCUITIZED SUBSTRATES UTILIZING SMOOTH-SIDED CONDUCTIVE LAYERS AS PART THEREOF	8/11/2010	12/854,252	2010-0328868	8/14/2012	8,242,376	Issued
2-04-018	US	CIRCUITIZED SUBSTRATE WITH IMPROVED IMPEDANCE CONTROL CIRCUITRY, METHOD OF MAKING SAME, ELECTRICAL ASSEMBLY AND INFORMATION HANDLING SYSTEM UTILIZING SAME	9/29/2004	10/953,923	2006-0065433	11/13/2007	7,294,791	Issued
2-04-018D	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE WITH IMPROVED IMPEDANCE CONTROL CIRCUITRY, ELECTRICAL ASSEMBLY AND INFORMATION HANDLING SYSTEM	8/15/2007	11/889,668	2007-0284140	9/15/2009	7,589,283	Issued
2-04-006	US	METHOD AND SYSTEM FOR TRACKING GOODS	6/4/2004	10/860,067	2005-0289019	6/23/2009	7,552,091	Issued
2-04-010	US	RADIO FREQUENCY DEVICE FOR TRACKING GOODS	6/4/2004	10/860,071	2005-0270160	11/28/2006	7,142,121	Issued
2-04-015	US	METHOD OF MAKING A CIRCUITIZED SUBSTRATE HAVING A PLURALITY OF SOLDER CONNECTION SITES THEREON	10/21/2004	10/968,929	2006-0099727	8/8/2006	7,087,441	Issued
2-04-008	US	HIGH SPEED CIRCUITIZED SUBSTRATE WITH REDUCED THRU-HOLE STUB, METHOD FOR FABRICATION AND INFORMATION HANDLING SYSTEM UTILIZING SAME	9/30/2004	10/955,741	2005-0039950	2/7/2006	6,995,322	Issued
IN-2-04-008	India	HIGH SPEED CIRCUITIZED SUBSTRATE W/REDUCED THRU-HOLE STUB, METHOD FOR FABRICATION AND INFORMATION HANDLING SYSTEM UTILIZING SAME		1828/DEL/2005				Pending
TW-2-04-008	Taiwan	HIGH SPEED CIRCUITIZED SUBSTRATE W/REDUCED THRU-HOLE STUB, METHOD FOR FABRICATION AND INFORMATION HANDLING SYSTEM UTILIZING SAME		94132230				Pending
2-05-025	US	SUBSTRATE TEST APPARATUS AND METHOD OF TESTING SUBSTRATES	11/18/2005	11/281,456		10/31/2006	7,129,732	Issued
2-05-001	US	INTERPOSER FOR USE WITH TEST APPARATUS	4/21/2005	11/110,901	2006-0238207	11/6/2007	7,292,055	Issued
2-05-001D	US	METHOD OF MAKING AN INTERPOSER	9/27/2007	11/902,976	2008-0020566	3/31/2009	7,511,518	Issued

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Docket No.	Country	Title	Filing Date	Appl. No.	Publication No.	Issued	Patent No.	Status
2-05-014	US	WIREBOND ELECTRONIC PACKAGE WITH ENHANCED CHIP PAD DESIGN, METHOD OF MAKING SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME	6/15/2005	11/152,048	2006-0284304	8/7/2007	7,253,518	Issued
2-05-014D	US	METHOD OF MAKING WIREBOND ELECTRONIC PACKAGE WITH ENHANCED CHIP PAD DESIGN	7/9/2007	11/822,573	2007-0254408	3/31/2009	7,510,912	Issued
2-05-010	US	MULTI-CHIP ELECTRONIC PACKAGE WITH REDUCED LINE SKEW AND CIRCUITIZED SUBSTRATE FOR USE THEREIN	5/12/2005	11/127,160	2006-0255460	2/19/2008	7,332,818	Issued
2-05-010D	US	METHOD OF MAKING MULTI-CHIP ELECTRONIC PACKAGE WITH REDUCED LINE SKEW	12/21/2007	12/003,299	2008-0102562	11/24/2009	7,622,384	Issued
2-04-017	US	CAPACITOR MATERIAL FOR USE IN CIRCUITIZED SUBSTRATES, CIRCUITIZED SUBSTRATE UTILIZING SAME, METHOD OF MAKING SAID CIRCUITIZED SUBSTRATE, AND INFORMATION HANDLING SYSTEM UTILIZING SAID CIRCUITIZED SUBSTRATE	1/10/2005	11/031,085	2006-0151863	6/2/2009	7,541,265	Issued
CN-2-04-017	China	CIRCUITIZED SUBSTRATES, CAPACITOR MATERIAL THEREFOR, THEIR PREPARATION METHOD, AND INFORMATION HANDLING SYSTEM COMPRISING SAME	12/28/2005	200510097424.5				Allowed
IN-2-04-017	India	CAPACITOR MATERIAL FOR USE IN CIRCUITIZED SUBSTRATES, CIRCUITIZED SUBSTRATE UTILIZING SAME, METHOD OF MAKING SAID CIRCUITIZED SUBSTRATE, AND INFORMATION HANDLING SYSTEM UTILIZING SAID CIRCUITIZED SUBSTRATES		3154/DEL/2005				Pending
2-05-006	US	PLATING METHOD FOR CIRCUITIZED SUBSTRATES	5/13/2005	11/128,272	2006-0255009	1/30/2007	7,169,313	Issued
2-05-016	US	METHOD OF TREATING CONDUCTIVE LAYER FOR USE IN A CIRCUITIZED SUBSTRATE AND METHOD OF MAKING SAID SUBSTRATE HAVING SAID CONDUCTIVE LAYER AS PART THEREOF	1/9/2006	11/327,493	2006-0121738	12/11/2007	7,307,022	Issued
2-05-016D	US	CIRCUITIZED SUBSTRATE WITH INCREASED ROUGHNESS CONDUCTIVE LAYER AS PART THEREOF	10/26/2007	11/976,629	2008-0054476			Pending
2-05-012	US	CIRCUITIZED SUBSTRATE WITH SINTERED PASTE CONNECTIONS, MULTILAYERED SUBSTRATE ASSEMBLY, ELECTRICAL ASSEMBLY AND INFORMATION HANDLING SYSTEM UTILIZING SAME	7/11/2005	11/177,442	2007-0007032	3/11/2008	7,342,183	Issued
2-05-012D	US	METHOD OF MAKING MULTILAYERED CIRCUITIZED SUBSTRATE ASSEMBLY	9/28/2007	11/905,188	2008-0022520	11/2/2010	7,823,274	Issued
2-05-013	US	METHOD OF MAKING MULTILAYERED CIRCUITIZED SUBSTRATE ASSEMBLY HAVING SINTERED PASTE CONNECTIONS	7/11/2005	11/177,413	2007-0006452	2/26/2008	7,334,323	Issued
2-05-013D	us	CIRCUITIZED SUBSTRATE WITH SINTERED PASTE CONNECTIONS AND MULTILAYERED SUBSTRATE ASSEMBLY HAVING SAID SUBSTRATE AS PART THEREOF	1/8/2008	12/007,178	2008-0105457			Pending
2-04-019	US	CIRCUITIZED SUBSTRATES UTILIZING THREE SMOOTH-SIDED CONDUCTIVE LAYERS AS PART THEREOF, METHOD OF MAKING SAME, AND ELECTRICAL ASSEMBLIES AND INFORMATION HANDLING SYSTEMS UTILIZING SAME	11/19/2004	10/991,451		11/15/2005	6,964,884	Issued
CN-2-04-019	China	CIRCUITIZED SUBSTRATES UTILIZING THREE SMOOTH-SIDED CONDUCTIVE LAYERS AS PART THEREOF, METHOD OF MAKING SAME, AND ELECTRICAL ASSEMBLIES AND INFORMATION HANDLING SYSTEMS UTILIZING SAME		200510115610.7				Pending
IN-2-04-019	India	CIRCUITIZED SUBSTRATES UTILIZING THREE SMOOTH-SIDED CONDUCTIVE LAYERS AS PART THEREOF, METHOD OF MAKING SAME, AND ELECTRICAL ASSEMBLIES AND INFORMATION HANDLING SYSTEMS UTILIZING SAME		2489/DEL/2005				Pending

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Docket No.	Country	Title	Filing Date	Appl. No.	Publication No.	Issued	Patent No.	Status
2-04-019D	US	CIRCUITIZED SUBSTRATES UTILIZING THREE SMOOTH-SIDED CONDUCTIVE LAYERS AS PART THEREOF AND ELECTRICAL ASSEMBLIES AND INFORMATION HANDLING SYSTEMS UTILIZING SAME	8/31/2005	11/215,206	2006-0180343			Pending
2-05-003	US	APPARATUS AND METHOD FOR MAKING CIRCUITIZED SUBSTRATES IN A CONTINUOUS MANNER	4/21/2005	11/110,919		11/13/2007	7,293,355	Issued
2-05-003D	US	APPARATUS FOR MAKING CIRCUITIZED SUBSTRATES IN A CONTINUOUS MANNER	8/3/2007	11/882,625	2007-0266555	2/12/2008	7,328,502	Issued
2-05-005	US	APPARATUS FOR MAKING CIRCUITIZED SUBSTRATES HAVING PHOTO-IMAGEABLE DIELECTRIC LAYERS IN A CONTINUOUS MANNER	4/21/2005	11/110,920	2006-0240364	11/9/2010	7,827,682	Issued
2-05-005D	US	METHOD FOR MAKING CIRCUITIZED SUBSTRATES HAVING PHOTO-IMAGEABLE DIELECTRIC LAYERS IN A CONTINUOUS MANNER	1/20/2010	12/657,394	2011-0173809	7/12/2011	7,977,034	Issued
2-05-017	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE	1/4/2006	11/324,432	2007-0166944	6/3/2008	7,381,587	issued
CN-2-05-017	China	METHOD OF MAKING CIRCUITIZED SUBSTRATE	12/21/2006	200610170522.1		7/11/2007	1,996,562	issued
TW-2-05-017	Taiwan	METHOD OF MAKING CIRCUITIZED SUBSTRATE	12/21/2006	95148292	95148292			Pending
2-04-020	US	CAPACITOR MATERIAL WITH METAL COMPONENT FOR USE IN CIRCUITIZED SUBSTRATES, CIRCUITIZED SUBSTRATE UTILIZING SAME, METHOD OF MAKING SAID CIRCUITIZED SUBSTRATE, AND INFORMATION HANDLING SYSTEM UTILIZING SAID CIRCUITIZED SUBSTRATE	1/10/2005	11/031,074		4/11/2006	7,025,607	Issued
2-04-020D	US	CAPACITOR MATERIAL WITH METAL COMPONENT FOR USE IN CIRCUITIZED SUBSTRATES, CIRCUITIZED SUBSTRATE UTILIZING SAME, METHOD OF MAKING SAID CIRCUITIZED SUBSTRATE, AND INFORMATION HANDLING SYSTEM UTILIZING SAID CIRCUITIZED SUBSTRATE	1/4/2006	11/324,273	2006-0154501			Pending
2-05-008	US	METHOD OF MAKING AN INTERNAL CAPACITIVE SUBSTRATE FOR USE IN A CIRCUITIZED SUBSTRATE AND METHOD OF MAKING SAID CIRCUITIZED SUBSTRATE	7/5/2005	11/172,794	2006-0154434	6/10/2008	7,384,856	Issued
2-05-009	US	RESISTOR MATERIAL WITH METAL COMPONENT FOR USE IN CIRCUITIZED SUBSTRATES, CIRCUITIZED SUBSTRATE UTILIZING SAME, METHOD OF MAKING SAID CIRCUITIZED SUBSTRATE, AND INFORMATION HANDLING SYSTEM UTILIZING SAID CIRCUITIZED SUBSTRATE	7/5/2005	11/172,786	2006-0151202	7/13/2006	7,235,745	Issued
2-05-009D	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE WITH A RESISTOR	5/2/2007	11/797,236	2008-0151515	1/18/2011	7,870,664	Issued
2-05-009D2	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE WITH RESISTOR INCLUDING MATERIAL WITH METAL COMPONENT AND ELECTRICAL ASSEMBLY AND INFORMATION HANDLING SYSTEM UTILIZING SAID CIRCUITIZED SUBSTRATE	11/3/2010	12/938,759	2011-0043987	8/21/2012	8,247,703	Issued
2-05-018	US	METHOD OF IMPROVING ELECTRICAL CONNECTIONS IN CIRCUITIZED SUBSTRATES	12/19/2005	11/305,073	2007-0139977	12/8/2009	7,629,559	Issued
2-05-015	US	METHOD AND APPARATUS FOR DEPOSITING CONDUCTIVE PASTE IN CIRCUITIZED SUBSTRATE OPENINGS	9/1/2005	11/216,133	2007-0048897	5/1/2007	7,211,470	Issued
2-06-001	US	ADJUSTABLE THICKNESS THERMAL INTERPOSER AND ELECTRONIC PACKAGE UTILIZING SAME	4/4/2006	11/396,711	2007-0230130	12/8/2009	7,629,684	Issued
2-05-028	US	METHOD OF FORMING FIBROUS LAMINATE CHIP CARRIER STRUCTURES	7/16/2010	12/837,584	2012-0012553			Pending
2-06-004	US	CAPACITIVE SUBSTRATE	5/23/2006	11/438,424	2007-0275525	3/1/2011	7,897,877	Issued
2-06-004D	US	CAPACITIVE SUBSTRATE AND METHOD OF MAKING SAME	3/2/2009	12/380,616	2009-0206051	9/28/2010	7,803,688	Issued
2-08-009	US	PHOTOSENSITIVE DIELECTRIC FILM	7/27/2009	12/460,975	2011-0017498			Pending
JP-2-05-023	Japan	METHOD OF MAKING A CIRCUITIZED SUBSTRATE HAVING A PLURALITY OF SOLDER CONNECTION SITES THEREON		2006-267024				Pending

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Docket No.	Country	Title	Filing Date	Appl. No.	Publication No.	Issued	Patent No.	Status
2-05-019	US	DIELECTRIC COMPOSITION FOR USE IN CIRCUITIZED SUBSTRATES AND CIRCUITIZED SUBSTRATE INCLUDING SAME	11/3/2005	11/265,287	2006-0054870	4/26/2011	7,931,830	Issued
IN-2-05-019	India	DIELECTRIC COMPOSITION FOR USE IN CIRCUITIZED SUBSTRATES AND CIRCUITIZED SUBSTRATE INCLUDING SAME		2164/DEL/2006				Pending
JP-2-05-019	Japan	DIELECTRIC COMPOSITION FOR USE IN CIRCUITIZED SUBSTRATES AND CIRCUITIZED SUBSTRATE INCLUDING SAME		2006-288641				Pending
2-05-021	US	CIRCUITIZED SUBSTRATE WITH SOLDER-COATED MICROPARTICLE PASTE CONNECTIONS, MULTILAYERED SUBSTRATE ASSEMBLY, ELECTRICAL ASSEMBLY AND INFORMATION HANDLING SYSTEM UTILIZIGN SAME AND METHOD OF MAKING SAID SUBSTRATE	10/6/2005	11/244,180	2007-0007033	10/28/2008	7,442,879	Issued
2-06-010	US	INTERPOSER AND TEST ASSEMBLY FOR TESTING ELECTRONIC DEVICES	12/4/2006	11/607,973	2007-0075726	3/10/2009	7,501,839	Issued
2-05-024	US	FLUOROPOLYMER DIELECTRIC COMPOSITION FOR USE IN CIRCUITIZED SUBSTRATES AND CIRCUITIZED SUBSTRATE INCLUDING SAME	3/28/2006	11/390,386	2006-0180936	9/30/2008	7,429,789	Issued
JP-2-05-024	Japan	FLUOROPOLYMER DIELECTRIC COMPOSITION FOR USE IN CIRCUITIZED SUBSTRATES AND CIRCUITIZED SUBSTRATE INCLUDING SAME		2007-081228				Pending
2-06-002	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE WITH SOLDER PASTE CONNECTIONS	11/14/2006	11/598,647	2008-0110016	6/16/2009	7,547,577	Issued
CN-2-06-002	China	METHOD OF MAKING CIRCUITIZED SUBSTRATE WITH SOLDER PASTE CONNECTIONS	11/5/2007	200710165173.9				Issued
IN-2-06-002	India	METHOD OF MAKING CIRCUITIZED SUBSTRATE WITH SOLDER PASTE CONNECTIONS		2156/DEL/2007				Pending
TW-2-06-002	Taiwan	METHOD OF MAKING CIRCUITIZED SUBSTRATE WITH SOLDER PASTE CONNECTIONS		96138518				Pending
2-05-026	US	METHOD OF MAKING A CAPACITIVE SUBSTRATE FOR USE AS PART OF A LARGER CIRCUITIZED SUBSTRATE, METHOD OF MAKING SAID CIRCUITIZED SUBSTRATE AND METHOD OF MAKING AN INFORMATION HANDLING SYSTEM INCLUDING SAID CIRCUITIZED SUBSTRATE	2/13/2006	11/352,279	2007-0010065	11/11/2008	7,449,381	Issued
2-05-027	US	METHOD OF MAKING A CAPACITIVE SUBSTRATE USING PHOTOIMAGEABLE DIELECTRIC FOR USE AS PART OF A LARGER CIRCUITIZED SUBSTRATE, METHOD OF MAKING SAID CIRCUITIZED SUBSTRATE AND METHOD OF MAKING AN INFORMATION HANDLING SYSTEM INCLUDING SAID CIRCUITIZED SUBSTRATE	2/13/2006	11/352,276	2007-0010064	9/30/2008	7,429,510	Issued
2-07-001	US	METHOD OF PROVIDING A PRINTED CIRCUIT BOARD WITH AN EDGE CONNECTION PORTION AND/OR A PLURALITY OF CAVITIES THEREIN	1/12/2007	11/652,633	2008-0168651	10/6/2009	7,596,863	Issued
HK-2-07-001	Hong Kong	METHOD OF PROVIDING A PRINTED CIRCUIT BOARD WITH AN EDGE CONNECTION PORTION AND/OR A PLURALITY OF CAVITIES THEREIN		9103246.7				Pending
IN-2-07-001	India	METHOD OF PROVIDING A PRINTED CIRCUIT BOARD WITH AN EDGE CONNECTION PORTION AND/OR A PLURALITY OF CAVITIES THEREIN		2709/DEL/2007				Pending
2-06-011	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE WITH SOLDER BALLS HAVING ROUGHENED SURFACES, METHOD OF MAKING ELECTRICAL ASSEMBLY INCLUDING SAID CIRCUITIZED SUBSTRATE, AND METHOD OF MAKING MULTIPLE CIRCUITIZED SUBSTRATE ASSEMBLY	1/8/2007	11/650,520	2008-0164300			Pending
2-06-015	US	CRENELLATED ISOLATION BORDER STRUCTURE AND METHOD	4/26/2012	13/456,535				Pending

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Docket No.	Country	Title	Filing Date	Appl. No.	Publication No.	Issued	Patent No.	Status
2-06-009	US	METHOD OF MAKING A CIRCUITIZED SUBSTRATE WITH ENHANCED CIRCUITRY AND ELECTRICAL ASSEMBLY UTILIZING SAID SUBSTRATE	11/1/2006	11/590,888	2008-0098595	9/29/2009	7,595,454	Issued
2-06-006	US	HIGH SPEED INTERPOSER	6/19/2006	11/454,896	2007-0289773	12/8/2009	7,629,541	Issued
2-06-006D1	US	HIGH SPEED INTERPOSER	1/24/2008	12/010,335	2008-0142258	1/25/2011	7,875,811	Issued
2-06-005	US	PHOTORESIST COMPOSITION WITH ANTIBACTERIAL AGENT	7/25/2006	11/492,029	2008-0026316	12/22/2009	7,635,552	Issued
2-06-007	US	SOLDER MASK APPLICATION PROCESS	8/8/2006	11/500,328	2008-0038670	10/16/2012	8,288,266	Issued
2-06-007D	US	CIRCUITIZED SUBSTRATE ASSEMBLY	9/12/2012	13/610,976				Pending
2-06-014	US	PRINTED CONDUCTIVE LINES WITH LOW RESISTIVITY	7/18/2011	13/184,699				Pending
2-06-008	US	HALOGEN-FREE CIRCUITIZED SUBSTRATE WITH REDUCED THERMAL EXPANSION, METHOD OF MAKING SAME, MULTILAYERED SUBSTRATE STRUCTURE UTILIZING SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME	10/3/2006	11/541,776	2008-0078570	3/30/2010	7,687,722	Issued
CN-2-06-008	China	HALOGEN-FREE CIRCUITIZED SUBSTRATE WITH REDUCED THERMAL EXPANSION, METHOD OF MAKING SAME, MULTILAYERED SUBSTRATE STRUCTURE UTILIZING SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME		200710161542.7				Pending
IN-2-06-008	India	HALOGEN-FREE CIRCUITIZED SUBSTRATE WITH REDUCED THERMAL EXPANSION, METHOD OF MAKING SAME, MULTILAYERED SUBSTRATE STRUCTURE UTILIZING SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME		2044/DEL/2007				Pending
2-06-008D	US	HALOGEN-FREE CIRCUITIZED SUBSTRATE WITH REDUCED THERMAL EXPANSION, METHOD OF MAKING SAME, MULTILAYERED SUBSTRATE STRUCTURE UTILIZING SAME, AND INFORMATION HANDLING SYSTEM UTILIZING SAME	3/2/2009	12/380,618	2009-0175000			Pending
2-07-003	US	METHOD OF MAKING CIRCUITIZED SUBSTRATE WITH SELECTED CONDUCTORS HAVING SOLDER THEREON	3/30/2007	11/730,212	2008-0241359	3/22/2011	7,910,156	Issued
2-06-016	US	CAPACITOR MATERIAL, CIRCUITIZED SUBSTRATE HAVING INTERNAL CAPACITOR COMPRISED OF SAID MATERIAL THEREIN AND ELECTRICAL ASSEMBLY INCLUDING SAID CIRCUITIZED SUBSTRATE	7/3/2012	13/540,645				Pending
2-07-002	US	FLEXIBLE CIRCUIT ELECTRONIC PACKAGE WITH STANDOFFS	3/26/2007	11/727,314	2008-0237840	12/14/2010	7,851,906	Issued
IN-2-07-002	India	FLEXIBLE CIRCUIT ELECTRONIC PACKAGE WITH STANDOFFS		422/DEL/2008				Pending
JP-2-07-002	Japan	FLEXIBLE CIRCUIT ELECTRONIC PACKAGE WITH STANDOFFS		2008-057976				Pending
TW-2-07-002	Taiwan	FLEXIBLE CIRCUIT ELECTRONIC PACKAGE WITH STANDOFFS		97106659				Pending
2-07-005	US	METHOD FOR MAKING A MULTILAYERED CIRCUITIZED SUBSTRATE	5/2/2007	11/797,232	2007-0199195	12/8/2009	7,627,947	Issued
CN-2-07-005	China	METHOD FOR MAKING A MULTILAYERED CIRCUITIZED SUBSTRATE	4/30/2008	200810094487.9	101299911			Issued
IN-2-07-005	India	METHOD FOR MAKING A MULTILAYERED CIRCUITIZED SUBSTRATE		887/DEL/2008				Pending
EP-2-07-005	Europe	METHOD FOR MAKING A MULTILAYERED CIRCUITIZED SUBSTRATE		8251545.3				Pending
JP-2-07-005	Japan	METHOD FOR MAKING A MULTILAYERED CIRCUITIZED SUBSTRATE		2008-114868				Pending
2-06-013	US	NON-FLAKING CAPACITOR MATERIAL, CAPACITIVE SUBSTRATE HAVING AN INTERNAL CAPACITOR THEREIN INCLUDING SAID NON-FLAKING CAPACITOR MATERIAL, AND METHOD OF MAKING A CAPACITOR MEMBER FOR USE IN A CAPACITIVE SUBSTRATE	4/4/2007	11/730,761	2007-0177331			Pending
2-07-006	US	ADHESIVE BLEED PREVENTION METHOD AND PRODUCT PRODUCED FROM SAME	7/31/2007	11/882,149	2009-0035455			Pending

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Docket No.	Country	Title	Filing Date	Appl. No.	Publication No.	Issued	Patent No.	Status
2-06-012	US	CIRCUITIZED SUBSTRATE WITH INTERNAL STACKED SEMICONDUCTOR CHIPS, METHOD OF MAKING SAME, ELECTRICAL ASSEMBLY UTILIZING SAME AND INFORMATION HANDLING SYSTEM UTILIZING SAME	4/9/2007	11/783,306	2008-0244902	9/21/2010	7,800,916	Pending
EP-2-06-012	Europe	CIRCUITIZED SUBSTRATE WITH INTERNAL STACKED SEMICONDUCTOR CHIPS, METHOD OF MAKING SAME, ELECTRICAL ASSEMBLY UTILIZING SAME AND INFORMATION HANDLING SYSTEM UTILIZING SAME		8251098.3				Pending
JP-2-06-012	Japan	CIRCUITIZED SUBSTRATE WITH INTERNAL STACKED SEMICONDUCTOR CHIPS, METHOD OF MAKING SAME, ELECTRICAL ASSEMBLY UTILIZING SAME AND INFORMATION HANDLING SYSTEM UTILIZING SAME		2008-098245				Pending
TW-2-06-012	Taiwan	CIRCUITIZED SUBSTRATE WITH INTERNAL STACKED SEMICONDUCTOR CHIPS, METHOD OF MAKING SAME, ELECTRICAL ASSEMBLY UTILIZING SAME AND INFORMATION HANDLING SYSTEM UTILIZING SAME		97111078				Pending
2-06-026	US	SINTERED METAL MIXTURE FOR Z-AXIS ELECTRICAL INTERCONNECTION	9/26/2012	13/626,961				Pending
2-07-008	US	CIRCUITIZED SUBSTRATE WITH CONDUCTIVE PASTE, ELECTRICAL ASSEMBLY INCLUDING SAID CIRCUITIZED SUBSTRATE AND METHOD OF MAKING SAID SUBSTRATE	5/23/2007	11/802,434	2007-0221404	11/22/2011	8,063,315	Issued
2-07-008D	US	CIRCUITIZED SUBSTRATE WITH CONDUCTIVE PASTE, ELECTRICAL ASSEMBLY INCLUDING SAID CIRCUITIZED SUBSTRATE AND METHOD OF MAKING SAID SUBSTRATE	10/4/2011	13/252,256	2012-0017437			Pending
IN-2-07-008	India	CIRCUITIZED SUBSTRATE WITH INTERNAL RESISTOR, METHOD OF MAKING SAID CIRCUITIZED SUBSTRATE AND ELECTRICAL ASSEMBLY UTILIZING SAID CIRCUITIZED SUBSTRATE		912/DEL/2008				Pending
JP-2-07-008	Japan	CIRCUITIZED SUBSTRATE WITH INTERNAL RESISTOR, METHOD OF MAKING SAID CIRCUITIZED SUBSTRATE AND ELECTRICAL ASSEMBLY UTILIZING SAID CIRCUITIZED SUBSTRATE		2008-127348				Pending
2-06-029	US	ELECTRICALLY CONDUCTIVE ADHESIVE (ECA) FOR MULTILAYER DEVICE INTERCONNECTS	8/5/2011	13/198,756	2013-0033827			Pending
2-07-009	US	METHOD OF PROVIDING A PRINTED CIRCUIT BOARD WITH AN EDGE CONNECTION PORTION	6/7/2007	11/808,140	2008-0301933	5/11/2010	7,712,210	Issued
2-07-013	US	POWER CORE FOR USE IN CIRCUITIZED SUBSTRATE AND METHOD OF MAKING SAME	5/18/2010	12/782,187	2011-0284273	6/12/2012	8,198,551	Issued
2-08-003	US	HIGH BANDWIDTH SEMICONDUCTOR BALL GRID ARRAY PACKAGE	11/4/2010	12/939,659	2012-0112345			Pending
2-07-004	US	LED LIGHTING ASSEMBLY AND LAMP UTILIZING SAME	4/2/2007	11/730,404	2008-0238323	11/30/2010	7,841,741	Issued
HK-2-07-004	Hong Kong	LED LIGHTING ASSEMBLY AND LAMP UTILIZING SAME		9103287.7				Pending
IN-2-07-004	India	LED LIGHTING ASSEMBLY AND LAMP UTILIZING SAME		642/DEL/2008				Pending
2-07-010C	US	SUBSTRATE HAVING INTERNAL CAPACITOR AND METHOD OF MAKING SAME	6/14/2012	13/517,776				Pending
2-07-040	US	DEFECTIVE CONDUCTIVE SURFACE PAD REPAIR FOR MICROELECTRONIC CIRCUIT CARDS	3/7/2011	13/041,655	2012-0228013			Pending
2-07-007	US	CIRCUITIZED SUBSTRATE WITH INTERNAL RESISTOR, METHOD OF MAKING SAID CIRCUITIZED SUBSTRATE, AND ELECTRICAL ASSEMBLY UTILIZING SAID CIRCUITIZED SUBSTRATE	6/4/2007	11/806,685	2008-0087459	3/30/2010	7,687,724	Issued

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Docket No.	Country	Title	Filing Date	Appl. No.	Publication No.	Issued	Patent No.	Status
JP-2-07-007	Japan	CIRCUITIZED SUBSTRATE WITH INTERNAL RESISTOR, METHOD OF MAKING SAID CIRCUITIZED SUBSTRATE, AND ELECTRICAL ASSEMBLY UTILIZING SAID CIRCUITIZED SUBSTRATE		2008-145499				Pending
TW-2-07-007	Taiwan	CIRCUITIZED SUBSTRATE WITH INTERNAL RESISTOR, METHOD OF MAKING SAID CIRCUITIZED SUBSTRATE, AND ELECTRICAL ASSEMBLY UTILIZING SAID CIRCUITIZED SUBSTRATE		97118394				Pending
EI-2-07-007D	US	CIRCUITIZED SUBSTRATE WITH INTERNAL RESISTOR, METHOD OF MAKING SAID CIRCUITIZED SUBSTRATE, AND ELECTRICAL ASSEMBLY UTILIZING SAID CIRCUITIZED SUBSTRATE	10/20/2009	12/589,239	2011-0039212			Pending
2-07-015	US	METHOD OF MAKING CIRCUITIZED ASSEMBLY INCLUDING A PLURALITY OF CIRCUITIZED SUBSTRATES	1/15/2008	12/007,704	2009-0178273			Pending
2-08-001	US	CIRCUITIZED SUBSTRATE AND METHOD OF MAKING SAME	3/28/2008	12/078,206	2009-0241332			Pending
2-08-010	US	METHOD OF FORMING MULTILAYER CAPACITORS IN A PRINTED CIRCUIT SUBSTRATE	10/22/2010	12/909,983	2012-0223047			Pending
2-07-023	US	METHOD FOR IMPREGNATING ORGANIC FIBER PAPERS, INCLUDING P-ARAMID PAPERS	7/7/2010	12/831,411				Pending
2-07-017	US	CIRCUITIZED SUBSTRATE WITH P-ARAMID DIELECTRIC LAYERS AND METHOD OF MAKING SAME	4/10/2008	12/081,051	2008-0191354	12/27/2011	8,084,863	Issued (CIP of EI-2-04-007)
2-07-017D	US	METHOD OF MAKING A CIRCUITIZED SUBSTRATE WITH CONTINUOUS THERMOPLASTIC SUPPORT FILM DIELECTRIC LAYERS	3/2/2009	12/380,637	2009-0258161			Pending
2-08-002	US	MULTILAYERED CIRCUITIZED SUBSTRATE WITH P-ARAMID DIELECTRIC LAYERS AND METHOD OF MAKING SAME	4/10/2008	12/081,042	2008-0191353	1/12/2010	7,646,098	Issued
2-08-002D	US	MULTILAYERED CIRCUITIZED SUBSTRATE WITH P-ARAMID DIELECTRIC LAYERS AND METHOD OF MAKING SAME	3/2/2009	12/380,617	2009-0173426	7/3/2012	8,211,790	Issued
2-07-028	US	CONDUCTIVE METAL NUB FOR ENHANCED ELECTRICAL INTERCONNECTION, AND INFORMATION HANDLING SYSTEM UTILIZING SAME	1/20/2011	13/009,922	2012-0243155			Pending
2-08-007	US	SPRING ACTUATED CLAMPING MECHANISM	6/25/2008	12/215,079	2009-0320280	10/4/2011	8,028,390	Issued
2-08-007D	US	METHOD OF APPLYING FORCE TO ELECTRICAL CONTACTS ON A PRINTED CIRCUIT BOARD	4/20/2011	13/090,676	2011-0197430	6/12/2012	8,196,281	Issued
2-08-023	US	CONDUCTIVE PASTE FOR DEVICE LEVEL INTERCONNECTS	9/17/2010	12/884,657	2012-0069531			Pending
2-08-006	US	A METHOD OF JOINING A SEMICONDUCTOR DEVICE/CHIP TO A PRINTED WIRING BOARD	7/16/2010	12/837,640	2012-0015532	8/14/2012	8,240,031	Issued
2-08-008	US	MULTI-LAYER EMBEDDED CAPACITANCE AND RESISTANCE SUBSTRATE CORE	9/9/2008	12/283,146	2010-0060381	9/7/2010	7,791,897	Issued
2-08-008D	US	MULTI-LAYER EMBEDDED CAPACITANCE AND RESISTANCE SUBSTRATE CORE	3/10/2010	12/720,849	2010-0167210	3/27/2012	8,144,480	Issued
2-08-024	US	METHOD FOR VIA PLATING IN ELECTRONIC PACKAGES CONTAINING FLUOROPOLYMER DIELECTRIC LAYERS	4/22/2010	12/765,110	2011-0260299			Pending
2-08-012	US	LIQUID CRYSTAL POLYMER LAYER FOR ENCAPSULATION AND IMPROVED HERMITICITY OF CIRCUITIZED SUBSTRATES	9/17/2010	12/884,392	2012-0069288	3/27/2012	8,143,530	Issued
2-08-016	US	SILICON INTERPOSER CONTAINING ACTIVE COMPONENTS AND AN INTEGRATED CONNECTOR	1/31/2012	13/362,135				Pending
2-08-025	US	NEW HIGH DENSITY PACKAGING-COMPUTING SYSTEM	4/8/2011	13/082,599	2012-0260063			Pending
2-08-021-1	US	CORELESS LAYER BUILDUP STRUCTURE	4/22/2010	12/764,993	2012-0160547			Pending
2-08-021-2	US	CORELESS LAYER BUILDUP STRUCTURE WITH LGA	4/22/2010	12/764,994	2012-0160544			Pending
2-08-021-3	US	CORELESS LAYER BUILDUP STRUCTURE WITH LGA AND JOINING LAYER	4/22/2010	12/764,997	2012-0031649			Pending
2-09-002	US	CONDUCTIVE PASTE COMPOSITION AND METHOD OF MAKING CIRCUITIZED SUBSTRATE	4/8/2011	13/082,502	2012-0257343			Pending

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Docket No.	Country	Title	Filing Date	Appl. No.	Publication No.	Issued	Patent No.	Status
2-09-003	US	SEMI-CONDUCTOR CHIP WITH COMPRESSIBLE CONTACT STRUCTURE AND ELECTRONIC PACKAGE UTILIZING SAME	7/15/2010	12/836,612	2012-0038046	6/12/2012	8,198,739	Issued
2-09-005	US	ELECTRONIC PACKAGE INCLUDING HIGH DENSITY INTERPOSER AND CIRCUITIZED SUBSTRATE ASSEMBLY UTILIZING SAME	11/30/2009	12/592,682	2011-0127664	3/26/2013	8,405,229	Issued
2-09-005D	US	ELECTRONIC PACKAGE INCLUDING HIGH DENSITY INTERPOSER AND CIRCUITIZED SUBSTRATE ASSEMBLY UTILIZING SAME	2/26/2013	13/776,777				Pending
2-09-005A	US	METHOD OF MAKING HIGH DENSITY INTERPOSER AND ELECTRONIC PACKAGE UTILIZING SAME	12/1/2009	12/592,734	2011-0126408	8/21/2012	8,245,392	Issued
2-09-008	US	HIGH DENSITY CONNECTOR FOR INTERCONNECTING FINE PITCH CIRCUIT PACKAGING STRUCTURES	5/28/2010	12/789,642	2010-0323558	7/5/2011	7,972,178	Issued
2-09-009	US	ELECTRONIC PACKAGE AND METHOD OF MAKING SAME	10/22/2010	12/910,020	2012-0162928			Pending
2-09-012	US	LIQUID CRYSTAL POLYMER (LCP) SURFACE LAYER ADHESION ENHANCEMENT	8/4/2011	13/197,804	2013-0033671			Pending
2-09-015	US	METHOD OF SMALL CAVITY FORMATION ON BURIED RESISTOR LAYER USING FUSION BONDING	4/8/2011	13/082,444	2012-0256722			Pending
2-10-001	US	CIRCUITIZED SUBSTRATE WITH DIELECTRIC INTERPOSER ASSEMBLY AND METHOD	12/20/2010	12/972,700		10/30/2012	8,299,371	Issued
2-10-001D	US	CIRCUITIZED SUBSTRATE WITH DIELECTRIC INTERPOSER ASSEMBLY AND METHOD	9/19/2012	13/622,478				Pending
2-10-002	US	ANTI-TAMPER MICROCHIP PACKAGE BASED ON THERMAL NANOFLUIDS OR FLUIDS	9/17/2010	12/884,421	2012-0068326	10/16/2012	8,288,857	Issued
2-10-003	US	LAND GRID ARRAY (LGA) CONTACT CONNECTOR MODIFICATION	10/14/2010	12/904,305	2012-0243147			Pending
2-10-004	US	CIRCUITIZED SUBSTRATE WITH LOW LOSS CAPACITIVE MATERIAL AND METHOD OF MAKING SAME	10/10/2011	13/269,770				Allowed
2-10-005	US	SOLDER AND ELECTRICALLY CONDUCTIVE ADHESIVE BASED INTERCONNECTS FOR CZT CRYSTAL ATTACH	1/26/2012	13/358,716				Pending
2-10-006	US	CIRCUITIZED SUBSTRATE WITH INTERNAL THIN FILM CAPACITOR AND METHOD OF MAKING SAME	3/8/2011	13/042,578	2012-0228014			Pending
2-10-007	US	POLYDIMETHYLSILOXANE (PDMS) RIGID-FLEX SUBSTRATE FOR ELECTRONICS, ELECTRICALLY CONDUCTIVE ADHESIVE (ECA), AND METHOD FOR MAKING SAME	4/17/2012	13/448,505				Pending
2-10-008	US	METAL BUMP CONTACT FOR FLEXIBLE SUBSTRATES, AND INFORMATION HANDLING SYSTEM UTILIZING SAME	7/19/2011	13/184,882				Pending
2-10-009	US	ELECTRONIC PACKAGE WITH THERMAL INTERPOSER AND METHOD OF MAKING SAME	2/8/2011	13/022,654				Pending
2-10-010	US	ELECTRONIC PACKAGE AND METHOD OF MAKING SAME	4/17/2012	13/448,574				Pending
2-10-011	US	INTEGRATED CIRCUIT DIE COVER PLATE AND THERMAL ADHESIVE FOR ANTI-TAMPERING PACKAGING	5/8/2012	13/466,164				Pending
2-10-012	US	THERMAL SUBSTRATE	7/25/2011	13/189,980				Pending
2-10-013	US	PROCESS TO PURIFY WASTEWATER GENERATED IN THE PROCESS OF HYDRO FRACTURING OF NON-CONVENTIONAL GEOLOGIC FORMATIONS	9/21/2011	13/238,392				Pending
2-10-014	US	MINIATURIZED ELECTRONICS PACKAGE FOR CLANDESTINE USE AND METHOD OF MAKING SAME	1/30/2012	13/360,935				Pending
2-10-015	US	RIGID-FLEX CIRCUIT BOARD	4/16/2012	13/447,701				Pending
2-10-016	US	PROCEDURE TO RUN FOLLOW ON PROCESSES FOR PRODUCT THAT WAS RUN ON THE OPTICAL REGISTRATION SYSTEM AT LAYUP/LAMINATIONS	4/16/2012	13/447,644				Pending
2-10-017	US	METHOD OF MAKING A DIMENSIONALLY STABLE CIRCUITIZED SUBSTRATE	11/21/2012	13/682,805				Pending
2-10-018	US	BUMPED CONNECTION FOR FLEX SUBSTRATES	9/22/2011	13/239,544				Pending
2-10-021	US	CIRCUITIZED SUBSTRATE WITH EMBEDDED CAPACITORS FOR SELF DESTRUCTIVE ANTI-TAMPER PACKAGIN	6/15/2012	13/523,956				Pending

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Docket No.	Country	Title	Filing Date	Appl. No.	Publication No.	Issued	Patent No.	Status
2-10-022	US	SELF DESTRUCTIVE INTEGRATED CIRCUIT DIE FOR ANTI-TAMPER PACKAGING	5/8/2012	13/466,181				Pending
2-11-006	US	CIRCUITIZED SUBSTRATE INCLUDING RFID TECHNOLOGY AND METHOD OF MAKING SAME	5/30/2012	13/483,600				Pending
2-11-007	US	THIN CORE ELECTRONIC PACKAGE AND METHOD OF MAKING SAME	8/31/2012	13/600,332				Pending
2-11-009	US	METHOD OF VERIFYING PRODUCT AUTHENTICITY	4/17/2012	13/448,778				Pending
2-11-010	US	HIGH PERFORMANCE COMPUTER WITH FIELD PROGRAMMABLE GATE ARRAY ACCELERATION	6/28/2012	13/535,432				Pending

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SCHEDULE B

Locations at which Debtor's business is conducted and at which the Collateral and records concerning Collateral are located:

Address	County	Record Owner of Location
1093 Clark Street Endicott, NY, 13760	Broome	Endicott Interconnect Technologies, Inc

"Permitted Liens" as used in this Agreement means:

Name of Secured Party	Collateral	Lien Position
M&T Bank	General assets	First
Integrian Holdings, LLC	General assets	Subject to subordination

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